

## N-channel 650 V, 0.42 $\Omega$ typ., 8 A MDmesh™ M2 Power MOSFET in a TO-220FP package

Datasheet - production data

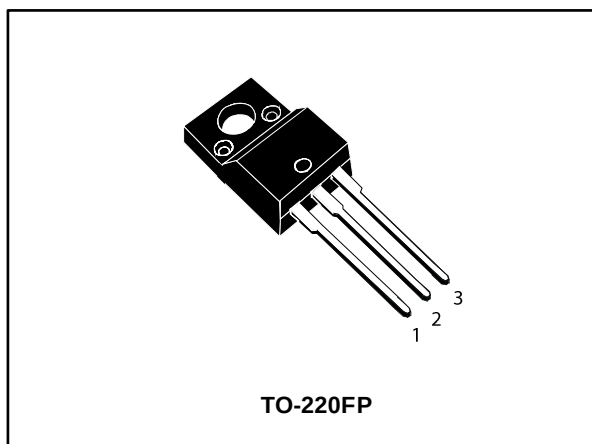
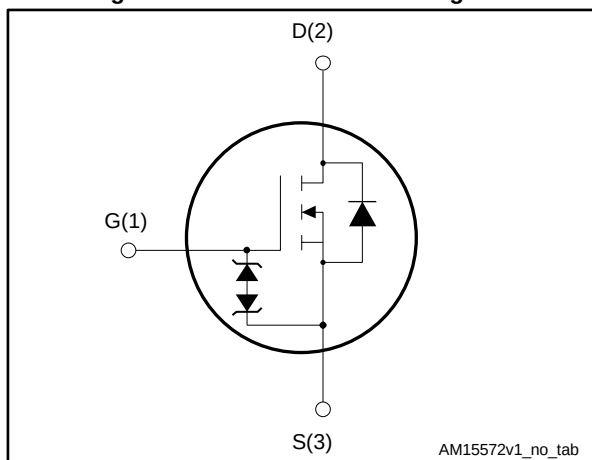


Figure 1: Internal schematic diagram



### Features

| Order code | V <sub>DS</sub> | R <sub>DS(on)</sub> max. | I <sub>D</sub> |
|------------|-----------------|--------------------------|----------------|
| STF12N65M2 | 650 V           | 0.50 $\Omega$            | 8 A            |

- Extremely low gate charge
- Excellent output capacitance (C<sub>oss</sub>) profile
- 100% avalanche tested
- Zener-protected

### Applications

- Switching applications

### Description

This device is an N-channel Power MOSFET developed using MDmesh™ M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.

Table 1: Device summary

| Order code | Marking | Package  | Packing |
|------------|---------|----------|---------|
| STF12N65M2 | 12N65M2 | TO-220FP | Tube    |

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## Contents

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# 1 Electrical ratings

Table 2: Absolute maximum ratings

| Symbol         | Parameter                                                                                                                               | Value      | Unit               |
|----------------|-----------------------------------------------------------------------------------------------------------------------------------------|------------|--------------------|
| $V_{GS}$       | Gate-source voltage                                                                                                                     | $\pm 25$   | V                  |
| $I_D^{(1)}$    | Drain current (continuous) at $T_{case} = 25\text{ }^{\circ}\text{C}$                                                                   | 8          | A                  |
|                | Drain current (continuous) at $T_{case} = 100\text{ }^{\circ}\text{C}$                                                                  | 5          |                    |
| $I_{DM}^{(2)}$ | Drain current (pulsed)                                                                                                                  | 32         | A                  |
| $P_{TOT}$      | Total dissipation at $T_{case} = 25\text{ }^{\circ}\text{C}$                                                                            | 25         | W                  |
| $dv/dt^{(3)}$  | Peak diode recovery voltage slope                                                                                                       | 15         | V/ns               |
| $dv/dt^{(4)}$  | MOSFET $dv/dt$ ruggedness                                                                                                               | 50         |                    |
| $V_{ISO}$      | Insulation withstand voltage (RMS) from all three leads to external heat sink ( $t = 1\text{ s}$ ; $T_C = 25\text{ }^{\circ}\text{C}$ ) | 2.5        | kV                 |
| $T_{stg}$      | Storage temperature range                                                                                                               | -55 to 150 | $^{\circ}\text{C}$ |
| $T_j$          | Operating junction temperature range                                                                                                    |            |                    |

**Notes:**

(1) Limited by package.

(2) Pulse width is limited by safe operating area.

(3)  $I_{SD} \leq 8\text{ A}$ ,  $di/dt = 400\text{ A}/\mu\text{s}$ ;  $V_{DS(peak)} < V_{(BR)DSS}$ ,  $V_{DD} = 400\text{ V}$ (4)  $V_{DS} \leq 520\text{ V}$ 

Table 3: Thermal data

| Symbol         | Parameter                           | Value | Unit                        |
|----------------|-------------------------------------|-------|-----------------------------|
| $R_{thj-case}$ | Thermal resistance junction-case    | 5     | $^{\circ}\text{C}/\text{W}$ |
| $R_{thj-amb}$  | Thermal resistance junction-ambient | 62.5  |                             |

Table 4: Avalanche characteristics

| Symbol         | Parameter                                                                                                              | Value | Unit |
|----------------|------------------------------------------------------------------------------------------------------------------------|-------|------|
| $I_{AR}$       | Avalanche current, repetitive or not repetitive (pulse width limited by $T_{jmax.}$ )                                  | 1.6   | A    |
| $E_{AS}^{(1)}$ | Single pulse avalanche energy (starting $T_j = 25\text{ }^{\circ}\text{C}$ , $I_D = I_{AR}$ ; $V_{DD} = 50\text{ V}$ ) | 250   | mJ   |

**Notes:**(1) Starting  $T_j = 25\text{ }^{\circ}\text{C}$ ,  $I_D = I_{AR}$ ,  $V_{DD} = 50\text{ V}$ .

## 2 Electrical characteristics

(T<sub>case</sub> = 25 °C unless otherwise specified)

**Table 5: Static**

| Symbol               | Parameter                         | Test conditions                                                                           | Min. | Typ. | Max. | Unit |
|----------------------|-----------------------------------|-------------------------------------------------------------------------------------------|------|------|------|------|
| V <sub>(BR)DSS</sub> | Drain-source breakdown voltage    | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA                                              | 650  |      |      | V    |
| I <sub>DSS</sub>     | Zero-gate voltage drain current   | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 650 V                                            |      |      | 1    | μA   |
|                      |                                   | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 600 V, T <sub>case</sub> = 125 °C <sup>(1)</sup> |      |      | 100  |      |
| I <sub>GSS</sub>     | Gate-body leakage current         | V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±25 V                                            |      |      | ±10  | μA   |
| V <sub>GS(th)</sub>  | Gate threshold voltage            | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA                               | 2    | 3    | 4    | V    |
| R <sub>DS(on)</sub>  | Static drain-source on-resistance | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4 A                                              |      | 0.42 | 0.50 | Ω    |

**Notes:**

<sup>(1)</sup>Defined by design, not subject to production test.

**Table 6: Dynamic**

| Symbol                              | Parameter                     | Test conditions                                                                                                                                      | Min. | Typ. | Max. | Unit |
|-------------------------------------|-------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------|------|------|------|------|
| C <sub>iss</sub>                    | Input capacitance             | V <sub>DS</sub> = 100 V, f = 1 MHz, V <sub>GS</sub> = 0 V                                                                                            | -    | 535  | -    | pF   |
| C <sub>oss</sub>                    | Output capacitance            |                                                                                                                                                      | -    | 25   | -    |      |
| C <sub>rss</sub>                    | Reverse transfer capacitance  |                                                                                                                                                      | -    | 1.1  | -    |      |
| C <sub>oss eq.</sub> <sup>(1)</sup> | Equivalent output capacitance | V <sub>DS</sub> = 0 to 520 V, V <sub>GS</sub> = 0 V                                                                                                  | -    | 144  | -    | pF   |
| R <sub>G</sub>                      | Intrinsic gate resistance     | f = 1 MHz, I <sub>D</sub> = 0 A                                                                                                                      | -    | 7    | -    | Ω    |
| Q <sub>g</sub>                      | Total gate charge             | V <sub>DD</sub> = 520 V, I <sub>D</sub> = 8 A, V <sub>GS</sub> = 0 to 10 V (see <a href="#">Figure 15: "Test circuit for gate charge behavior"</a> ) | -    | 16.7 | -    | nC   |
| Q <sub>gs</sub>                     | Gate-source charge            |                                                                                                                                                      | -    | 2.6  | -    |      |
| Q <sub>gd</sub>                     | Gate-drain charge             |                                                                                                                                                      | -    | 8.6  | -    |      |

**Notes:**

<sup>(1)</sup> C<sub>oss eq.</sub> is defined as a constant equivalent capacitance giving the same charging time as C<sub>oss</sub> when V<sub>DS</sub> increases from 0 to 80% V<sub>DSS</sub>.

**Table 7: Switching times**

| Symbol              | Parameter           | Test conditions                                                                                                                                                                                                                              | Min. | Typ. | Max. | Unit |
|---------------------|---------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|------|------|------|
| t <sub>d(on)</sub>  | Turn-on delay time  | V <sub>DD</sub> = 325 V, I <sub>D</sub> = 4 A<br>R <sub>G</sub> = 4.7 Ω, V <sub>GS</sub> = 10 V (see <a href="#">Figure 14: "Test circuit for resistive load switching times"</a> and <a href="#">Figure 19: "Switching time waveform"</a> ) | -    | 9    | -    | ns   |
| t <sub>r</sub>      | Rise time           |                                                                                                                                                                                                                                              | -    | 7    | -    |      |
| t <sub>d(off)</sub> | Turn-off delay time |                                                                                                                                                                                                                                              | -    | 34   | -    |      |
| t <sub>f</sub>      | Fall time           |                                                                                                                                                                                                                                              | -    | 13.5 | -    |      |

Table 8: Source-drain diode

| Symbol          | Parameter                     | Test conditions                                                                                                                                                                                                                            | Min. | Typ. | Max. | Unit          |
|-----------------|-------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|------|------|---------------|
| $I_{SD}^{(1)}$  | Source-drain current          |                                                                                                                                                                                                                                            | -    |      | 8    | A             |
| $I_{SDM}^{(2)}$ | Source-drain current (pulsed) |                                                                                                                                                                                                                                            | -    |      | 32   | A             |
| $V_{SD}^{(3)}$  | Forward on voltage            | $V_{GS} = 0\text{ V}$ , $I_{SD} = 8\text{ A}$                                                                                                                                                                                              | -    |      | 1.6  | V             |
| $t_{rr}$        | Reverse recovery time         | $I_{SD} = 8\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ ,<br>$V_{DD} = 60\text{ V}$ (see <a href="#">Figure 16</a> :<br>"Test circuit for inductive load<br>switching and diode recovery<br>times")                                     | -    | 313  |      | ns            |
| $Q_{rr}$        | Reverse recovery charge       |                                                                                                                                                                                                                                            | -    | 2.7  |      | $\mu\text{C}$ |
| $I_{RRM}$       | Reverse recovery current      |                                                                                                                                                                                                                                            | -    | 17   |      | A             |
| $t_{rr}$        | Reverse recovery time         | $I_{SD} = 8\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ ,<br>$V_{DD} = 60\text{ V}$ , $T_j = 150\text{ }^\circ\text{C}$ (see<br><a href="#">Figure 16</a> : "Test circuit for<br>inductive load switching and<br>diode recovery times") | -    | 462  |      | ns            |
| $Q_{rr}$        | Reverse recovery charge       |                                                                                                                                                                                                                                            | -    | 4.1  |      | $\mu\text{C}$ |
| $I_{RRM}$       | Reverse recovery current      |                                                                                                                                                                                                                                            | -    | 17.5 |      | A             |

**Notes:**

<sup>(1)</sup>Limited by package.

<sup>(2)</sup> Pulse width is limited by safe operating area.

<sup>(3)</sup> Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

Figure 2: Safe operating area

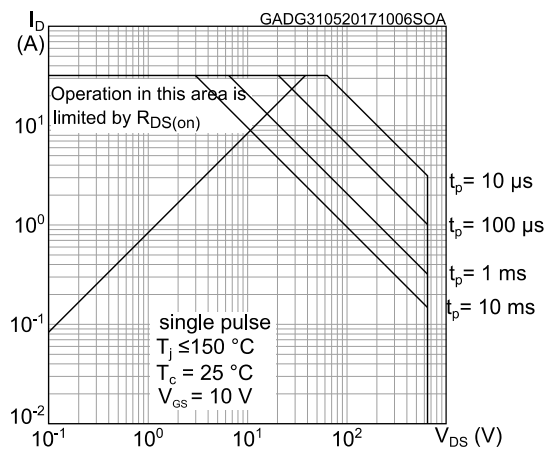


Figure 3: Thermal impedance

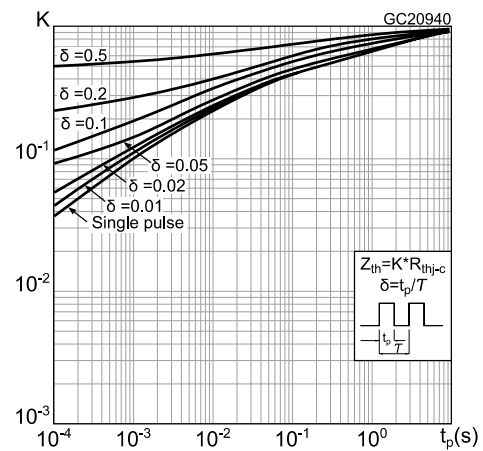


Figure 4: Output characteristics

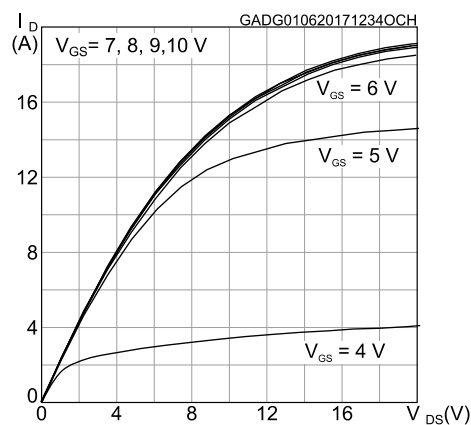


Figure 5: Transfer characteristics

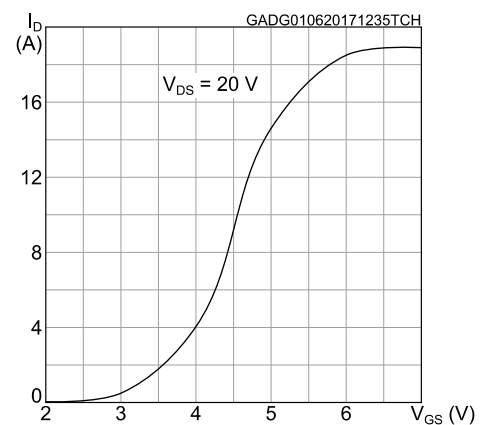


Figure 6: Gate charge vs gate-source voltage

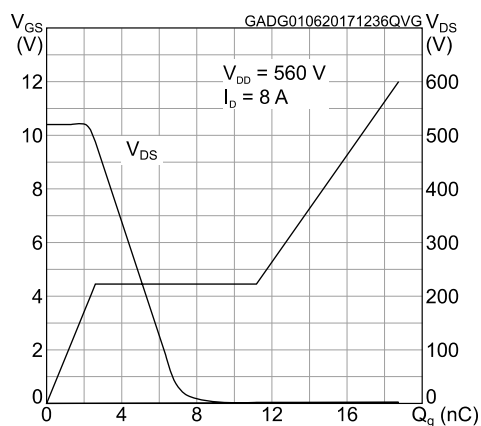


Figure 7: Static drain-source on-resistance

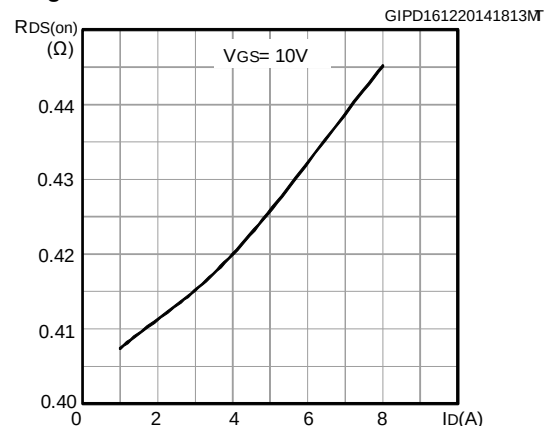


Figure 8: Capacitance variations

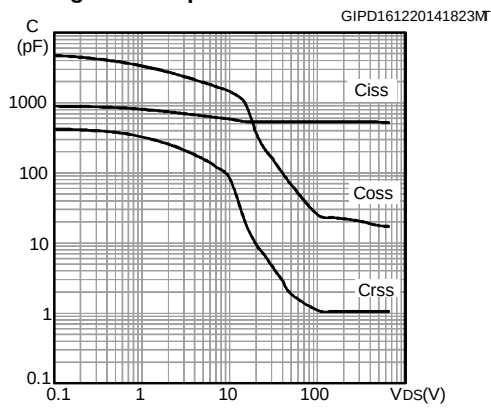


Figure 9: Normalized gate threshold voltage vs temperature

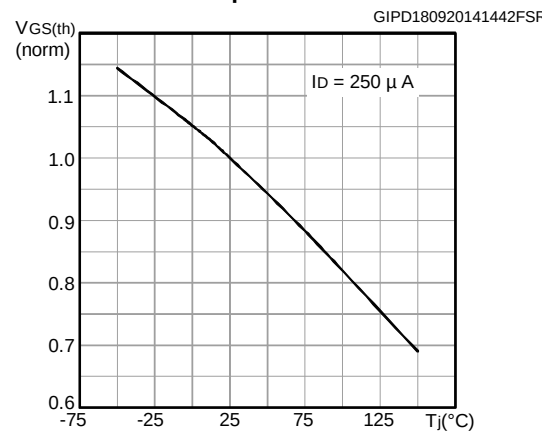


Figure 10: Normalized on-resistance vs temperature

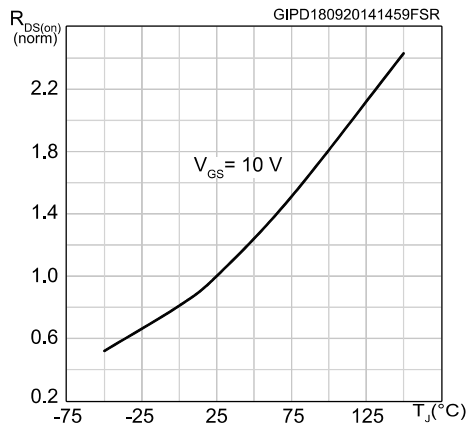


Figure 11: Normalized V(BR)DSS vs temperature

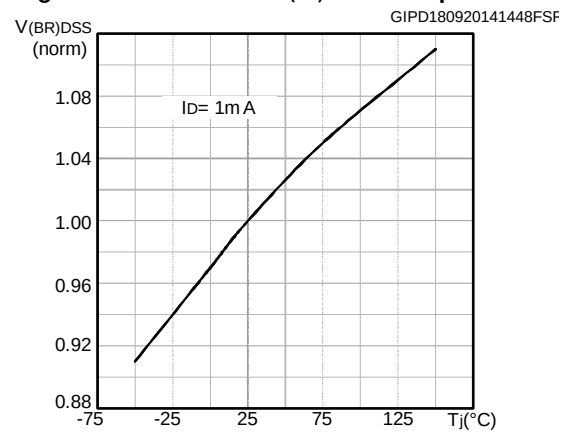


Figure 12: Output capacitance stored energy

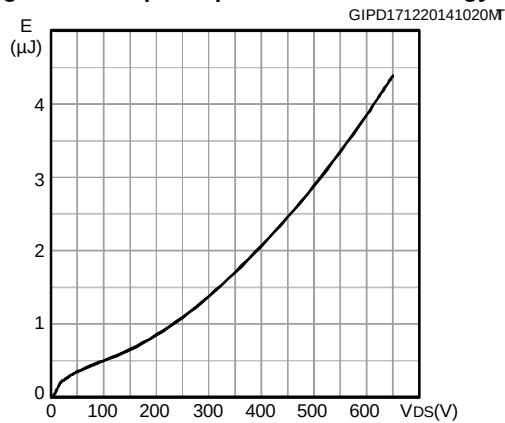
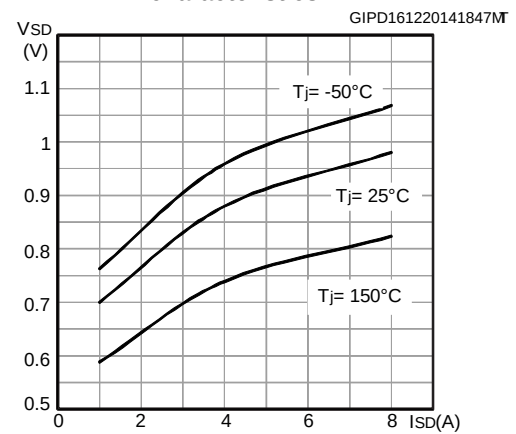
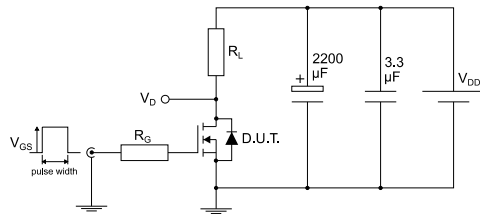


Figure 13: Source-drain diode forward characteristics



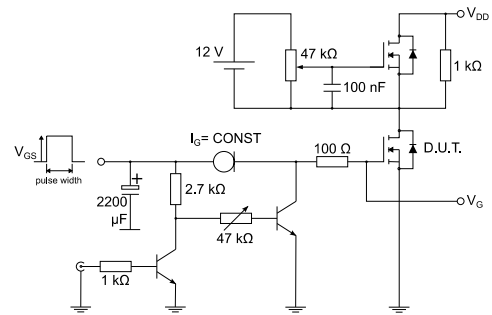
### 3 Test circuits

**Figure 14: Test circuit for resistive load switching times**



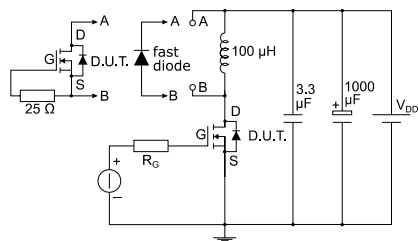
AM01468v1

**Figure 15: Test circuit for gate charge behavior**



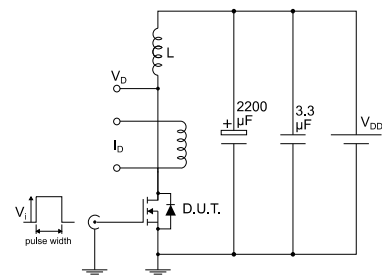
AM01469v1

**Figure 16: Test circuit for inductive load switching and diode recovery times**



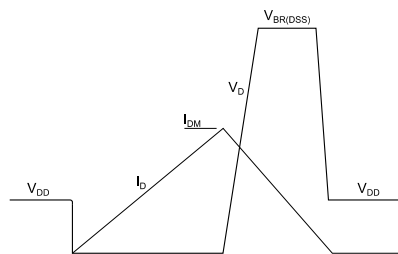
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**Figure 17: Unclamped inductive load test circuit**



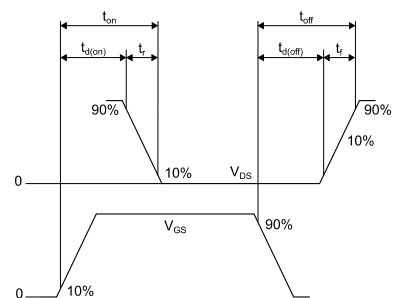
AM01471v1

**Figure 18: Unclamped inductive waveform**



AM01472v1

**Figure 19: Switching time waveform**



AM01473v1

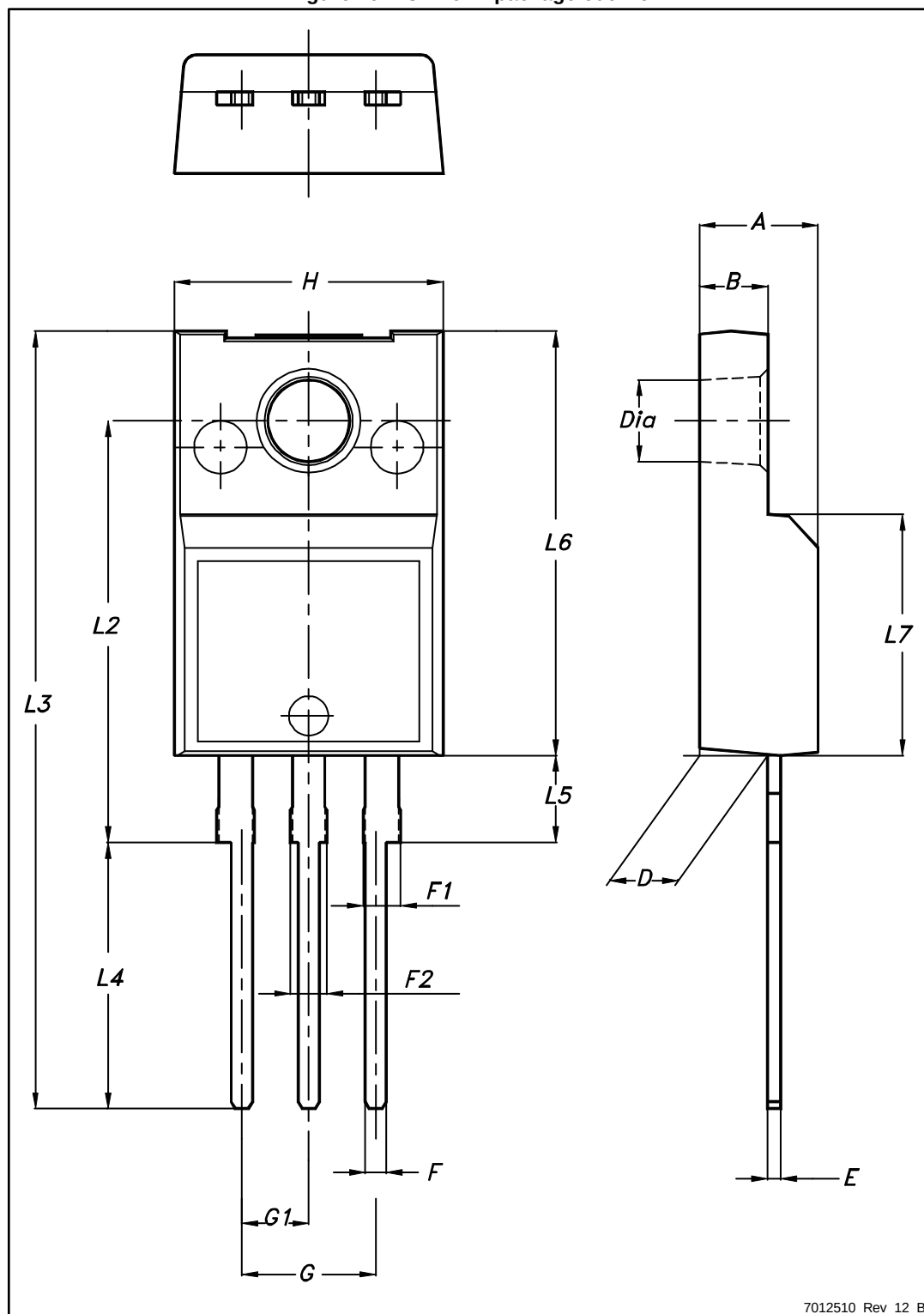


## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **[www.st.com](http://www.st.com)**. ECOPACK® is an ST trademark.

## 4.1 TO-220FP package information

Figure 20: TO-220FP package outline



7012510\_Rev\_12\_B

Table 9: TO-220FP package mechanical data

| Dim. | mm   |      |      |
|------|------|------|------|
|      | Min. | Typ. | Max. |
| A    | 4.4  |      | 4.6  |
| B    | 2.5  |      | 2.7  |
| D    | 2.5  |      | 2.75 |
| E    | 0.45 |      | 0.7  |
| F    | 0.75 |      | 1    |
| F1   | 1.15 |      | 1.70 |
| F2   | 1.15 |      | 1.70 |
| G    | 4.95 |      | 5.2  |
| G1   | 2.4  |      | 2.7  |
| H    | 10   |      | 10.4 |
| L2   |      | 16   |      |
| L3   | 28.6 |      | 30.6 |
| L4   | 9.8  |      | 10.6 |
| L5   | 2.9  |      | 3.6  |
| L6   | 15.9 |      | 16.4 |
| L7   | 9    |      | 9.3  |
| Dia  | 3    |      | 3.2  |

## 5 Revision history

Table 10: Document revision history

| Date        | Revision | Changes                                                                                                                                                         |
|-------------|----------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 16-Dec-2014 | 1        | First release.                                                                                                                                                  |
| 11-Mar-2015 | 2        | Updated features in cover page. Minor text changes                                                                                                              |
| 06-Jun-2017 | 3        | Updated <i>Section 1: "Electrical ratings"</i> , <i>Section 2: "Electrical characteristics"</i> and <i>Section 2.1: "Electrical characteristics (curves)"</i> . |

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